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TID #: TIDA-03029



TIDA-03029 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1, C9	2	1uF	GRM219R71E105KA88D	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X7R, 0805	0805
2	C2	1	0.047uF	GRM155R71E473KA88D	MuRata	CAP, CERM, 0.047 µF, 25 V, +/- 10%, X7R, 0402	0402
3	C3, C4, C6	3	10uF	GRM21BR71A106KE51L	MuRata	CAP, CERM, 10 µF, 10 V, +/- 10%, X7R, 0805	0805
4	C5	1	4.7uF	GRM188R61C475KAAJ	MuRata	CAP, CERM, 4.7 µF, 16 V, +/- 10%, X5R, 0603	0603
5	C7	1	8.2pF	GRM1555C1E8R2CA01D	MuRata	CAP, CERM, 8.2 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
6	C10	1	2.2uF	GRM21BR71A225KA01L	MuRata	CAP, CERM, 2.2 μF, 10 V, +/- 10%, X7R, 0805	0805
7	C11	1	0.47uF	GRM188R70J474KA01D	MuRata	CAP, CERM, 0.47 µF, 6.3 V, +/- 10%, X7R, 0603	0603
8	C12	1	4.7uF	GRM188C71A475KE11D	MuRata	CAP, CERM, 4.7 µF, 10 V, +/- 10%, X7S, 0603	0603
9	C13, C14	2	10pF	GRM1555C1H100JA01D	MuRata	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
10	C15, C16	2	0.22uF	GRM188R70J224KA88D	MuRata	CAP, CERM, 0.22 µF, 6.3 V, +/- 10%, X7R, 0603	0603
11	C17, C19, C20		0.1uF	GRM155R70J104KA01D	MuRata	CAP, CERM, 0.1 µF, 6.3 V, +/- 10%, X7R, 0402	0402
12	C18	1	10uF	293D106X96R3A2TE3	Vishay-Sprague	CAP, TA, 10 µF, 6.3 V, +/- 10%, 3.4 ohm, SMD	3216-18
13	C21, C22	2	12pF	GRM1555C1H120JA01D	MuRata	CAP, CERM, 12 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
14	C23	1	1000pF	GRM033R71C102KA01D	MuRata	CAP, CERM, 1000 pF, 16 V, +/- 10%, X7R, 0201	0201
15	C24, C25, C26,	4	1000pF	GRM033R71E102KA01D	MuRata	CAP, CERM, 1000 pF, 25 V, +/- 10%, X7R, 0201	0201
13	C24, C23, C20,	1 7	ТОООРІ	GRW033R7 IE 102RA01B	Multata	CAI , CERW, 1000 pi , 23 V, +/- 10/6, A/R, 0201	0201
16	D1	1	Green	LTST-C190GKT	Lite-On	LED, Green, SMD	1.6x0.8x0.8mm
17	D2	1	30V	BAT54C-7-F	Diodes Inc.	Diode, Schottky, 30 V, 0.2 A, SOT-23	SOT-23
18	J1, J4	2	30 V	0473460001	Molex	Connector, Receptacle, Micro-USB Type B, R/A, Bottom Mount SMT	7.5x2.45x5mm
19		2		1727010	Phoenix Contact	Conn Term Block, 2POS, 3.81mm, TH	2POS Terminal Block
19	J2, J3	2		1727010	Phoenix Contact	Conn Term Block, 2POS, 3.81mm, TH	2POS Terminai Biock
20	L1	1	1uH	IHLP2020BZER1R0M11	Vishay-Dale	Inductor, Shielded Drum Core, Powdered Iron, 1 µH, 7 A, 0.0181 ohm,	5.49x2x5.18mm
						SMD	
21	R1, R2, R14	3	0	CRCW20100000Z0EF	Vishay-Dale	RES, 0, 5%, 0.75 W, AEC-Q200 Grade 0, 2010	2010
22	R3, R6, R8, R9,	6	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
	R15, R18					1	6
23	R4	1	5.23k	CRCW04025K23FKED	Vishay-Dale	RES, 5.23 k, 1%, 0.063 W, 0402	0402
24	R5		30.1k	CRCW040230K1FKED	Vishay-Dale	RES, 30.1 k, 1%, 0.063 W, 0402	0402
25	R7	1	2.21k	CRCW04022K21FKED	Vishay-Dale	RES, 2.21 k, 1%, 0.063 W, 0402	0402
26	R10, R11	2	27	CRCW120627R0JNEA	Vishay-Dale	RES, 27, 5%, 0.25 W, 1206	1206
27	R12	1	1.40k	CRCW04021K40FKED	Vishay-Dale	RES, 1.40 k, 1%, 0.063 W, 0402	0402
28	R13	1	1.0Meg	CRCW04021M00JNED	Vishay-Dale	RES, 1.0 M, 5%, 0.063 W, 0402	0402
29	R16	1	47k	CRCW040247K0JNED	Vishay-Dale	RES, 47 k, 5%, 0.063 W, 0402	0402
30	R17	1	100	CRCW0402100RJNED	Vishay-Dale	RES, 100, 5%, 0.063 W, 0402	0402
31	R20	1	4.7k	CRCW04024K70JNED	Vishay-Dale	RES, 4.7 k, 5%, 0.063 W, 0402	0402
32	S1, S2	2		KSR221GLFS	C&K Components	Switch, Normally open, 2.3N force, 200k operations, SMD	KSR
33	U1	1		BQ25890HRTWR	Texas Instruments	1S 5A Fast Charger MaxCharge Technology for High Input Voltage and	RTW0024H
						Adjustable USB OTG Boost, RTW0024H (WQFN-24)	
34	U2	1		MSP430F5529IPN	Texas Instruments	25 MHz Mixed Signal Microcontroller with 128 KB Flash, 8192 B SRAM	PN0080A
						and 63 GPIOs, -40 to 85 degC, 80-pin QFP (PN), Green (RoHS & no	
						Sb/Br)	
35	U3	1		TPS70930DBVR	Texas Instruments	150-mA, 30-V, 1-uA IQ Voltage Regulator with Enable, DBV0005A	DBV0005A
36	Y1	1		CSTCR4M00G15L99-R0	MuRata	Resonator, 4MHz, 39pF SMD	4.5x1.2x2 mm
37	Y2	1		MS3V-T1R 32.768KHZ +/-	Micro Crystal AG	Crystal, 32.768kHz, 12.5pF, SMD	1.4x1.4x5.0mm SMD
		1		20PPM 12.5PF	1 ,		1

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